



## Product Change Notification - LIAL-04CMGK362

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**Date:**

25 Mar 2020

**Product Category:**

8-bit Microcontrollers; Switching Regulators; Temperature Sensors; Memory; Capacitive Touch Sensors; Power Management - Power Switches; Camera Flash LED Drivers; Power Management - System Supervisors/Voltage Detectors

**Affected CPNs:**



**Notification subject:**

CCB 4134 Initial Notice: Qualification of JCP2 as a new bumping facility for selected products available in 4L WLCSP, 5L WLCSP, 6L WLCSP, 8L WLCSP, 9L WLCSP, 12L WLCSP and 16L WLCSP packages.

**Notification text:**

**PCN Status:**

Initial notification.

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of JCP2 as a new bumping facility for selected products available in 4L WLCSP, 5L WLCSP, 6L WLCSP, 8L WLCSP, 9L WLCSP, 12L WLCSP and 16L WLCSP packages.

**Pre Change:**

Bumping facility at JCAP

**Post Change:**

Bumping facility at JCP2

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Bumping facility</b>	JIANGYIN CHANGDIAN ADVANCED PACKAGING LTD  B1 Line (JCAP)	JIANGYIN CHANGDIAN ADVANCED PACKAGING LTD  B2 Line (JCP2)

**Impacts to Data Sheet:**

None



**Change Impact:**

None

**Reason for Change:**

To improve on time delivery performance by qualifying JCP2 as a new bumping facility

**Change Implementation Status:**

In Progress

**Estimated Qualification Completion Date:**

July 2020

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

	March 2020					-->	July 2020				
Workweek	10	11	12	13	14		27	28	29	30	31
Initial PCN Issue Date				X							
Qual Report Availability									X		
Final PCN Issue Date									X		

**Method to Identify Change:**

Traceability code

**Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan

**Revision History:**

**March 25, 2020:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_LIAL-04CMGK362\\_Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

**Terms and Conditions:**

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.



# **QUALIFICATION PLAN SUMMARY**

**PCN#: LIAL-04CMGK362**

**Date**  
**March 18, 2020**

**Qualification of JCP2 as a new bumping facility for selected products available in 4L WLCSP, 5L WLCSP, 6L WLCSP, 8L WLCSP, 9L WLCSP, 12L WLCSP and 16L WLCSP packages.**

**Purpose:** Qualification of JCP2 as a new bumping facility for selected products available in 4L WLCSP, 5L WLCSP, 6L WLCSP, 8L WLCSP, 9L WLCSP, 12L WLCSP and 16L WLCSP packages.

**Package/Die Data:**

<b>Assembly site</b>	JCAP B2
<b>BD number</b>	D-004250
<b>CCB</b>	4134
<b>Qual rev</b>	C
<b>MPN</b>	TKKA1TFBAA04
<b>CPN</b>	MIC2782DRYCS-TR
<b>Mask</b>	TKKA1
<b>Package Group</b>	WLCSP
<b>Pin count</b>	6
<b>PI material</b>	PI
<b>UBM composition</b>	Ti/Cu/Cu
<b>UBM size</b>	230 um
<b>Ball size</b>	250 um
<b>Ball pitch</b>	0.4 mm

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot	# of CSP Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Required/Info	Special Instructions	Test Format
Temp Cycle	-40°C to 125°C for 1000 cycles. Electrical test pre and post stress at +25°C (required).	77 units*	5	3	82	0	15	Required	Spares should be properly identified.	CSP Board Level Data

LIAL-04CMGK362 - CCB 4134 | 5L WLCSP 6L WLCSP 8L WLCSP 9L WLCSP 12L WLCSP and 16L WLCSP packag

Affected Catalog Part Numbers(CPN)

MIC2873YCS-TR  
MIC2874YCS-T5  
MIC2874YCS-TR  
MIC23156-0YCS-TR  
MIC23156-2YCS-TR  
MIC94161YCS-TR  
MIC94162YCS-TR  
MIC94163YCS-TR  
MIC94164YCS-TR  
MIC94165YCS-TR  
AT42QT1050-UUR  
ATTINY20-UUR  
AT30TS74-UFM13-T  
AT30TS74-UFM10-T-072  
AT30TS74-UFM11-T-072  
AT30TS74-UFM12-T-072  
AT30TS74-UFM13-T-072  
AT30TS74-UFM14-T-072  
AT30TS74-U1FMAB-T  
AT30TS74-U1FMBB-T  
AT30TS74-U1FMCB-T  
AT30TS74-U1FMDB-T  
AT30TS74-U1FMEB-T  
AT30TS74-U1FMFB-T  
AT30TS74-U1FMGB-T  
AT30TS74-U1FMHB-T  
AT24C64D-U2UM0B-T  
AT24C64D-UUM0B-T  
AT24C128C-UUM0B-T  
AT24CM02-U1UM0B-T  
AT24C08D-UUM0B-T  
AT24C08D-UUM0B-T-894  
AT24C16D-UUM0B-T  
AT24C32E-UUM0B-T  
AT21CS01-U1UM0B-F  
24CW640T-I/CS0668  
MIC2782CLYCS-TR  
MIC2782CRYCS-TR  
MIC2782DLYCS-TR  
MIC2782DRYCS-TR  
MIC2782ELYCS-TR  
MIC2782EMYCS-TR

MIC2782FLYCS-TR  
MIC2782FRYCS-TR